

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.48686	100.0	5.2
Subtotal				0.48686	100	5.2
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00468	2.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0.00585	2.5	0.0625
	Lead alloy	Lead (Pb)	7439-92-1	0.22353	95.5	2.3875
Subtotal				0.23406	100	2.5
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03574	100.0	0.3817
	Pure metal	Aluminium (Al)	7429-90-5	0.09307	100.0	0.99402
Subtotal				0.12881	200	1.37572
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03754	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01126	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03754	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.4578	99.77	400.0777
Subtotal				37.54414	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84474	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.92655	10.0	63.3
	Filler	Silica fused	60676-86-0	50.37564	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11853	0.2	1.266
Subtotal				59.26546	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34066	100.0	25
Subtotal				2.34066	100	25
Total				99.99999	100	1068.07572

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.